



PTO/SB/05A(10-01)
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Substitute Disclosure Statement Form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)		Complete if Known Application Number 09/483,881 Filing Date January 18, 2000 First Named Inventor Ahn, Kie Group Art Unit 2812 Examiner Name Nguyen, Ha				
Sheet 1 of 1		Attorney Docket No: 303.672US1				

US PATENT DOCUMENTS						
Examiner Initials*	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
lhm	US-2002/0167089A1	11/14/2002	Ahn, Kie Y., et al.	257	762	05/14/2001
	US-5,240,878	08/31/1993	Fitzsimmons, J., et al.	437	187	04/26/1991
	US-6,065,424	05/23/2000	Shacham-Diamond, Y., et al.	118	696	12/18/1996
	US-6,358,849	03/19/2002	Havemann, R. H., et al.	438	689	12/21/1999
	US-6,552,432	04/22/2003	Farrar, Paul A.	257	751	08/30/2001
	US-6,614,099	09/02/2003	Farrar, Paul A.	257	643	09/04/2001
	US-6,743,716	06/01/2004	Farrar, Paul A.	438	652	07/16/2002
↓	US-6,756,298	06/29/2004	Ahn, Kie Y., et al.	438	635	08/01/2002

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Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²

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lhm		AMERICAN SOCIETY FOR METALS, "Properties and Selection: Nonferrous Alloys and Pure Metals", <u>Metals Handbook</u> , 9th ed., vol. 2, Metals Park, Ohio,(1979),Table of Contents				
lhm		VAN HORN, K. R., "Aluminum Vol. III Fabrication and Finishing", <u>American Society for Metals</u> , Metals Park, OH,(1967),468				

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**INFORMATION DISCLOSURE
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First Named Inventor	Ahn, Kie
Group Art Unit	2812
Examiner Name	Nguyen, Ha

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jm		AMERICAN SOCIETY FOR METALS, "Properties and Selection: Nonferrous Alloys and Pure Metals", <u>Metals Handbook</u> , 9th ed., vol. 2, Metals Park, Ohio,(1979),Table of Contents	
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INFORMATION DISCLOSURE STATEMENT BY APPLICANT <small>(Use as many sheets as necessary)</small> <div style="text-align: center; border: 1px solid black; border-radius: 50%; width: 100px; height: 100px; margin: 10px auto;"> <div style="position: absolute; top: 15px; left: 15px; font-size: 2em;">MAY 16 2005</div> <div style="position: absolute; top: 20px; left: 20px; font-size: 1em;">JCA</div> <div style="position: absolute; bottom: 10px; left: 10px; font-size: 0.8em;">PATENT & TRADEMARK OFFICE</div> </div>			
		Completes if Known	
		Application Number	09/483,881
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		Group Art Unit	2812
Examiner Name	Nguyen, Ha		
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Han		MURARKA, S. P., et al., "Copper Metallization for ULSI and Beyond", <u>Critical Reviews in Solid State and Materials Sciences</u> , 20(2), (1995), 87-124		

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Han

DATE CONSIDERED 07-18-05

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M		BHANSALI, S., et al., "Selective seeding of copper films on polyimide-patterned silicon substrate, using ion implantation", <u>Sensors and Actuators A: Physical</u> , 52(1), (March 1996), 126-131	

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